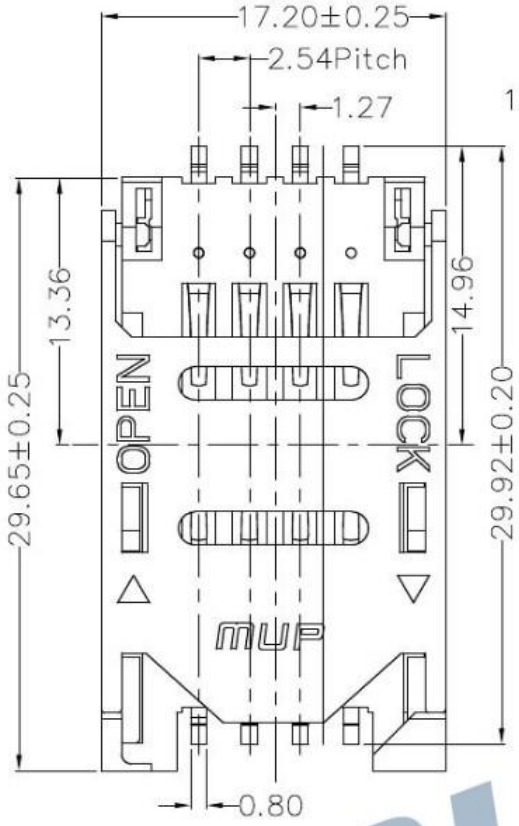
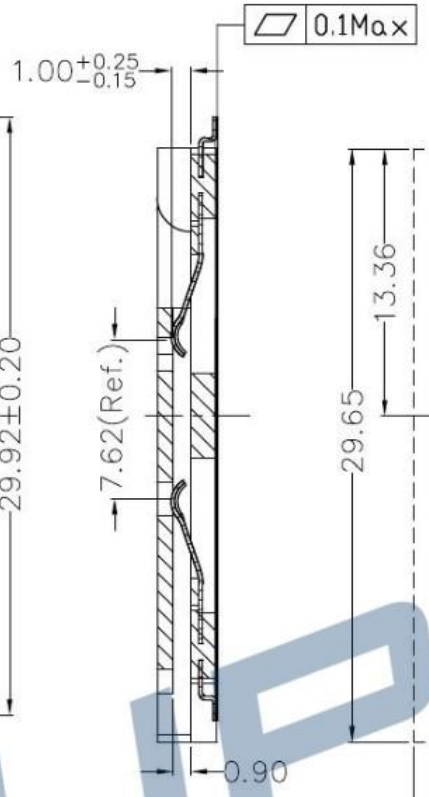
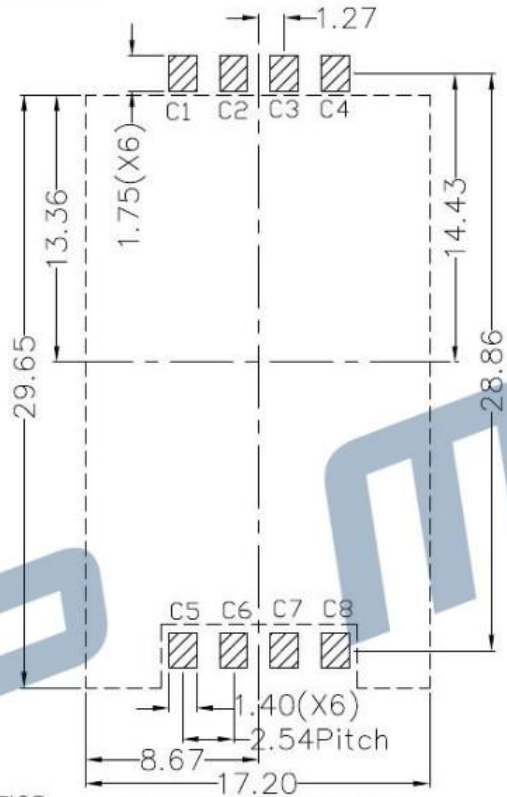
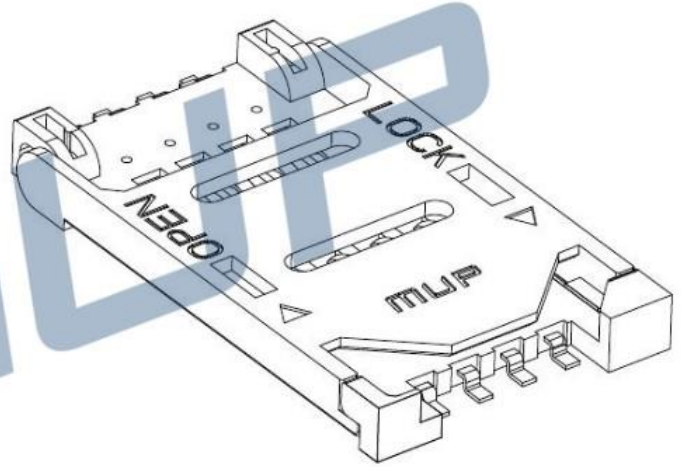
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					

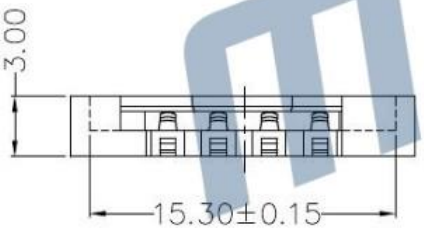






RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)





TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 29.65LX17.20WX3.00H mm

Weight: Approx 1.30±0.2g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Black UL94V-0
3	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

X ±0.35	X° ±5°		
X.X ±0.25	X.X° ±4°		
X.XX ±0.15	X.XX° ±3°		
X.XXX ±0.10	X.XXX° ±2°		

PROJ. | UNIT mm | SCALE 1:1

CUSTOMER DRAWING

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C712-2**

TYPE : **H3.0 without post 8p**

DRAWN	Zoey Mar.10.2006	DWG NO.: DWG-MUP-C712-002
CHECKED	Jimmy Mar.10.2006	
APPROVAL	Simon Mar.10.2006	SHEET 1/1 / REVISION X1

MUP MUP